

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Nishant Sinha

**Serial No.:** 10/668,914

**Filed:** September 23, 2003

**For:** PROCESS AND INTEGRATION  
SCHEME FOR FABRICATING  
CONDUCTIVE COMPONENTS,  
THROUGH-VIAS AND  
SEMICONDUCTOR COMPONENTS  
INCLUDING CONDUCTIVE THROUGH-  
WAFER VIAS

**Confirmation No.:** 2525

**Examiner:** W. Lindsay Jr.

**Group Art Unit:** 2812

**Attorney Docket No.:** 2269-5859US

**VIA ELECTRONIC FILING  
July 31, 2007**

**COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE**

Mail Stop Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

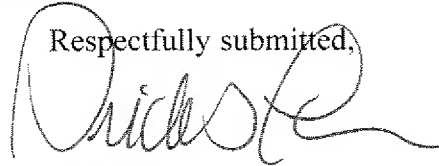
Sir:

On June 26, 2007, the Office mailed a communication in the above-referenced application in which an additional statement of reasons for allowance was presented. That statement follows: "examiner believes this references [sic] [U.S. Patent 4,605,471 to Mitchell] is only missing the steps of forming a partial via and the introduction of a filler."

It is respectfully submitted that use of the term "steps" in the above-stated reasons for allowance is inapplicable to the allowed claims, which are drawn to "intermediate semiconductor

device component[s]” rather than methods. Further, the scope of each allowed claim should be based upon its plain language, rather than the above-stated reasons for allowance, and the full scope of equivalents available to the recited elements.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Brick G. Power", written over the typed name.

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Date: July 31, 2007

BGP/eg

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